

## Application:

Intel LGA775 Wolfdale / Yorkfield (45nm) CPU  
E8000/E7000/E6000/E5000/Q9000S/Q8000S  
sequence

## Thermal & Mechanical Spec.:

Thermal performance for 65W CPU  
HSK Assembly Weight: 205 g (ref.)  
Clipping Force: 20 Kgf (ref.)

## Picture:



## Component Specification:

- Heat Sink  
Type: Extruded HSK  
Material: Aluminum A6063 or Equivalent.  
Dimension: 90\*90\*19.05 mm
- Thermal interface material  
Material: Dow Corning TC-1996 or Equivalent.
- Fan  
*(90x90x25 mm with Thermistor & PWM Control)*

Rated Voltage: 12 V

Life Time:

Superflo bearing 50000 hrs

Connector:

a. Lead wire: UL 1430 AWG#26

pin 1: black wire-----(-)

pin 2: yellow wire-----(+)

pin 3: green wire----- (F00)

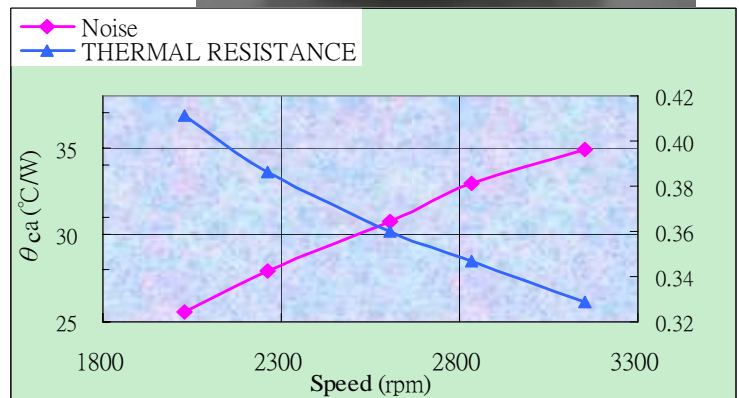
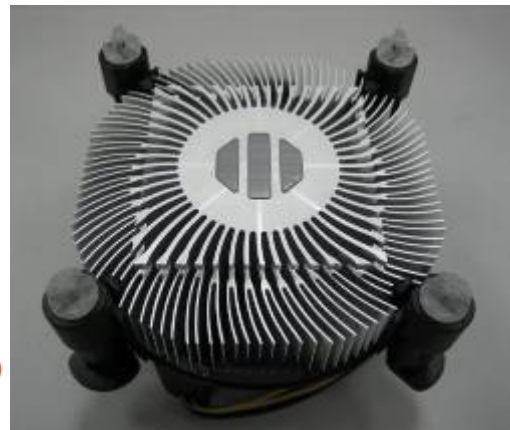
pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent

\* All readings are typical values at rated voltage.

\* Specifications are subject to change without notice



## Application:

Intel LGA775 Conroe-L Celeron CPU 400 series

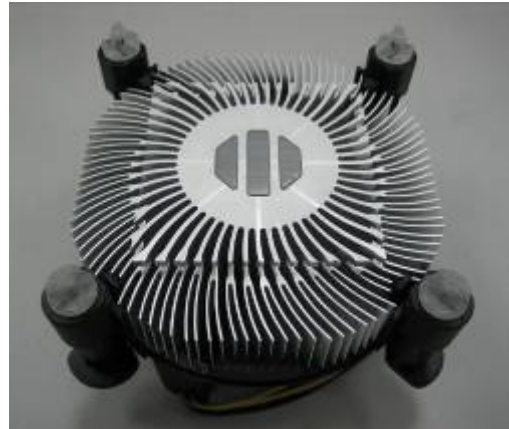
## Thermal & Mechanical Spec.:

Thermal performance for 35W CPU  
HSK Assembly Weight: 205 g (ref.)  
Clipping Force: 20 Kgf (ref.)

## Component Specification:

- Heat Sink  
Type: Extruded HSK  
Material: Aluminum A6063 or Equivalent.  
Dimension: 90\*90\*19.05 mm
- Thermal interface material  
Material: Dow Corning TC-1996 or Equivalent.
- Fan *(90x90x25 mm with single speed)*  
Rated Voltage: 12 V  
Life Time:  
Superflo bearing 50000 hrs  
Connector:
  - Lead wire: UL 1430 AWG#26  
pin 1: black wire-----(-)  
pin 2: yellow wire-----(+)  
pin 3: green wire----- (F00)
  - Housing: Molex 2695-03 22-01-3037 or equivalent
  - Terminal: Molex 2759T 08-50-0113 or equivalent

## Picture:



- \* All readings are typical values at rated voltage.
- \* Specifications are subject to change without notice

## Application:

Intel LGA775 Yorkfield (45nm) CPU  
Q9000/Q8000 sequence (Low Profile)

## Thermal & Mechanical Spec.:

Thermal performance for 95W CPU  
HSK Assembly Weight: 290 g (ref.)  
Clipping Force: 20 Kgf (ref.)

## Picture:

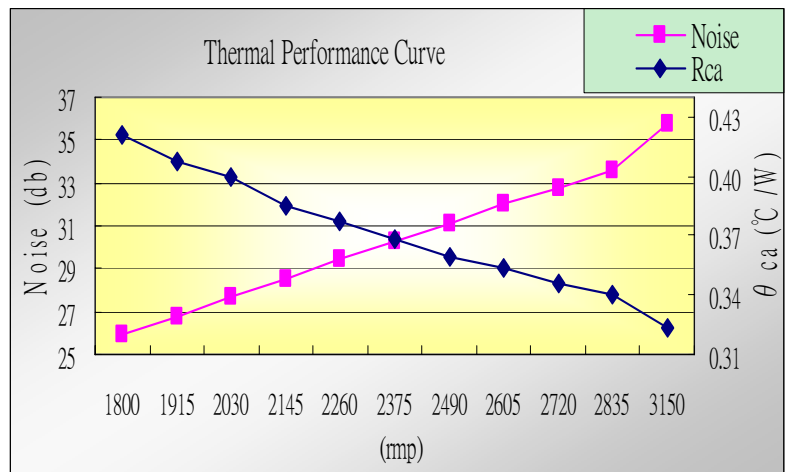


## Component Specification:

- Heat Sink  
Type: Thermal Shrink with Cu Core  
Material: Aluminum A6063 & Copper C1100 or Equivalent.  
Dimension: 90\*90\*19.05 mm
- Thermal interface material  
Material: Dow Corning TC-1996 or Equivalent.
- Fan *(90x90x25 mm with Thermistor & PWM Control)*  
Rated Voltage: 12 V  
Life Time:  
Superflo bearing 50000 hrs  
Connector:



- Lead wire: UL 1430 AWG#26  
pin 1: black wire-----(-)  
pin 2: yellow wire-----(+)  
pin 3: green wire----- (F00)  
pin 4: blue wire----- (PWM)
- Housing: Molex 47054-1000 or equivalent
- Terminal: Molex 2759T 08-50-0113 or equivalent



- \* All readings are typical values at rated voltage.
- \* Specifications are subject to change without notice